

PMP5327_REVC BOM

| COUNT | RefDes | Value | Description | Size | Part Number | Mfr |
|-------|------------------------------|-------------|--|--------------------|----------------------|---------------------|
| 1 | C1 | 150uF | Capacitor, Aluminum, 400V, 20% | 30 x 40 mm | EETED2G151DA | Panasonic |
| 1 | C10 | 0.22uF | Capacitor, Ceramic, 16V, X7R, 10% | 0603 | C1608X7R1C224K | TDK |
| 1 | C11 | 150pF | Capacitor, Ceramic, 50V, C0G, 10% | 0603 | STD | STD |
| 1 | C12 | 0.1uF | Capacitor, Ceramic, 250V, X7R, 10% | 1206 | C3216X7R2E104K | TDK |
| 1 | C13 | 3.3uF | Capacitor, Ceramic, 16V, X7R, 15% | 0805 | STD | STD |
| 2 | C14, C37 | 22uF | Capacitor, Ceramic, 16V, X7R, 20% | 1206 | C3216X7R1C226M | TDK |
| 5 | C16, C17, C25, C29, C35 | 0.1uF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H104K | TDK |
| 6 | C19, C20, C21, C22, C23, C36 | 3.3uF | Capacitor, Ceramic, 50V, X7R, 15% | 1210 | STD | STD |
| 3 | C2, C3, C4 | 0.47uF | Capacitor, Film, 250VAC, 20% | 0.335 X 1.004 inch | ECQU2A474ML | Panasonic |
| 1 | C24 | 330uF | Capacitor, Aluminum Electrolytic, 50V | 0.315 inch | 50V ZL 330uF 10 X 23 | Rubycon |
| 1 | C26 | 0.022uF | Capacitor, Leaded, 630 VDC | 4.00 x 13.00 mm | BFC2 420 12203 | Vishay |
| 1 | C27 | 220pF | Capacitor, Ceramic, 1kV, C0G | 1808 | Std | Std |
| 1 | C28 | 1500pF | CAP, CERM DISC Y1, 250Vac, 20% | .500 X .310 | ECKDNA152ME | Panasonic |
| 2 | C31, C32 | 0.01uF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H103K | TDK |
| 1 | C33 | 0.047uF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H473K | TDK |
| 1 | C34 | 1uF | Capacitor, Ceramic, 50V, X7R, 15% | 1206 | Std | Std |
| 1 | C38 | 0.022uF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H103K | TDK |
| 1 | C39 | 22pF | Capacitor, Ceramic, 50V, C0G, 10% | 0603 | STD | STD |
| 1 | C40 | 4700pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H472K | TDK |
| 4 | C5, C15, C18, C30 | 1uF | Capacitor, Ceramic, 16V, X7R, 10% | 0603 | C1608X7R1C105K | TDK |
| 2 | C6, C8 | 1000pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H102K | TDK |
| 1 | C7 | 0.47uF | Capacitor, Ceramic, 16V, X7R, 10% | 0603 | C1608X7R1C474K | TDK |
| 1 | C9 | 1200pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H122K | TDK |
| 1 | D1 | MURS360 | Diode, 3A, 600V | SMC | MURS360 | ON Semi |
| 2 | D11, D14 | MBR20H150CT | Diode, Dual Schottky, 10A, 150V | TO-220 | MBR20H150CT | Vishay |
| 1 | D15 | 12V | Diode, Zener, 12-V | SOT23 | BZX84C12LT1 | ON Semiconductor |
| 2 | D18, D19 | MBR0560 | Diode, Schottky, 500-mA, 60-V | SOD123 | MBR0560 | STD |
| 1 | D2 | LXA04T600 | Diode, UltraFast Rectifier, 4-A, 600-V | TO220AC | LXA04T600 | Qspeed |
| 1 | D3 | GBU6J | Diode, Bridge Rectifier, 6A, 600V | 0.880 x 0.140 inch | GBU6J | Fairchild |
| 2 | D4, D5 | MURA160T3 | Diode, Rectifier, 1A, 600V | SMA | MURA160T3 | ON Semiconductor |
| 1 | D6 | BAS21 | Diode, Switching, 200-mA, 200-V, 330-mW | SOT23 | BAS21 | Zetex |
| 3 | D7, D10, D13 | MMSD914 | Diode, Switching, 100-V, 200-mA, 225-mW | SOD-123 | MMSD914T1 | On Semi |
| 1 | D8 | 5.1V | Diode, Zener, 5.1-V | SOT23 | BZX84C5V1LT1 | ON Semiconductor |
| 4 | D9, D12, D16, D17 | BAV99 | Diode, Dual Ultra Fast, Series, 200-mA, 70-V | SOT23 | BAV99 | Fairchild |
| 1 | F1 | 6.3A/250V | Fuse, TR5 Series, 6.3A, 250V | 0.335 | 3701630041 | Wickmann |
| 1 | HS1 | 287-1AB | Heatsink, TO-220, Vert. 65°C@4W | 0.5 x 1.000 inch | 287-1AB | Wakefield Eng. |
| 3 | HS2, HS3, HS4 | 513201 | HEATSINK TO-220 W/PINS 1inch TALL | 0.5x1.38in. | 531002B02500G | Aavid |
| 1 | J1 | 703W-00/54 | Connector, AC Board mount, 9mm | 1.97 x 0.79 | 703W-00/54 | Qualtek Electronics |
| 4 | J2, J3, J4, J5 | B2P-VH | Connector, Top Entry 2-pin, 156 mil spacing | 0.465 X 0.370 inch | B2P-VH | JST |
| 1 | L1 | 3 mH | Inductor, PFC Choke | 42.00 mm Dia. | RLTI-1019 | Renco |
| 1 | L2 | 100uH | Inductor, Radial Leaded | 23.00 Dia. mm | CL-1920-100LF | GCI |
| 1 | L3 | 4.7mH | Inductor, Power Choke, 3.5A | 1.043 x 1.457 inch | ET35V-472LF | GCI |
| 1 | L4 | 2mH | Inductor, 0.2A SMD | 0.300 sq" | DRQ74-471-R | Coiltronics |
| 2 | L5, L7 | 150uH | Inductor, SMT, 0.81A, 590milliohm | 0.300 sq" | DR74-151-R | Coiltronics |
| 1 | L6 | 1.0 uH | Inductor, Power Choke | 0.600 inch | PCV-0-102-10L | Coilcraft |
| 1 | Q1 | IPP50R199CP | Trans, Nchan, 550V, 6.6A, 199 milliohm | TO-220AB | IPP50R199CP | Infineon |
| 3 | Q2, Q6, Q9 | MMBT2907 | Bipolar, PNP, 60V, 600mA | SOT23 | MMBT2907LT1 | On Semiconductor |

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|-------|------------------------|--------------|--|--------------------|-----------------|-------------------|
| 1 | Q3 | FQD1N80TF | MOSFET, N-ch, 800V, 1A, 20 ohm | DKPAK | FQD1N80TF | FAIRCHILD |
| 2 | Q4, Q8 | MMBT2222A | Bipolar, NPN, 40V, 600mA | SOT23 | MMBT2222ALT1 | ON Semiconductor |
| 2 | Q5, Q7 | IRFB11N50A | Trans, Nchan, 500V, 11A, 520 milliohm | TO-220AB | IRFB11N50A | Vishay |
| 5 | R1, R24, R26, R30, R38 | 10k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R10 | 13.3k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 3 | R11, R20, R35 | 100k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 2 | R12, R39 | 33.2k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R14 | 1.8MEG | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R15 | 150k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 2 | R16, R32 | 1k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R18 | 2k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 4 | R2, R4, R17, R19 | 499k | Resistor, Chip, 1/16W, 1% | 1206 | Std | Std |
| 2 | R21, R29 | 20k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R22 | 0.5 | Resistor, 500 milliOhm, 1W, 5% | 2512 | STD | STD |
| 1 | R27 | 0 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R28 | 4.99k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R3 | 0.1 | Resistor, 2W, Wirewound, Non-Inductive | 0.130 * 0.600" | WNCR10FECT-ND | Ohmite |
| 2 | R31, R40 | 49.9k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R33 | 100 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R34 | 2.94k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R36 | 3.16k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R37 | 348k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R41 | 715 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R42 | 237k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 3 | R5, R23, R25 | 3 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 2 | R6, R7 | 3.3MEG | Resistor, Chip, 1/16W, 1% | 1206 | Std | Std |
| 1 | R8 | 221 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 2 | R9, R13 | 165k | Resistor, Chip, 1/16W, 1% | 1206 | Std | Std |
| 1 | RT1 | 2.5 Ohms | Thermistor, Inrush, 2.5 Ohms, 11-A | 0.236 X 0.512 | B57364S0259M000 | EPCOS |
| 1 | T1 | 340 uH | Xfmr, Resonant Half Bridge, 10% | 24.50 x 31.50 mm | RLTI-1009 | Renco |
| 1 | T2 | 56P3362 | Transformer, Gate Drive | 0.453 x 0.492 inch | 56P3362 | Vitec Electronics |
| 4 | TP3, TP5, TP7, TP8 | 5000 | Test Point, Red, Thru Hole Color Keyed | 0.100 x 0.100 inch | 5000 | Keystone |
| 3 | TP4, TP6, TP9 | 5001 | Test Point, Black, Thru Hole Color Keyed | 0.100 x 0.100 inch | 5001 | Keystone |
| 1 | U1 | UCC28019AD | IC, Continuous Current Mode PFC Controller | SO8 | UCC28019AD | TI |
| 1 | U2 | UCC2889 | IC, Off-line power supply controller | SO8 | UCC2889D | Texas Instruments |
| 1 | U3 | TL331DBV | IC, COMPARATOR, DIFFERENTIAL, SINGLE | SOT_23_5 (DBV) | TL331DBV | TI |
| 1 | U4 | UCC25600D | IC, Resonant Mode Controller | SO-8 | UCC25600D | TI |
| 1 | U5 | H11A817A | IC, Optocoupler, 5300-V, 80-160% CTR | 0.380 x 0.180 inch | H11A817A | Fairchild |
| 1 | U6 | TL431AIDBZ | IC, Precision Adjustable Shunt Regulator | SOT23-3 | TL431AIDBZ | TI |
| 1 | U7 | TPS54060ADGQ | IC, 0.5A, 60V Step-Down Converter | MSOP-10 | TPS54060ADGQ | TI |

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